

CHEMICAL MECHANICAL PLANARIZATION (CMP) SYSTEM AND METHOD FOR PREPARING A WAFER IN A CLEANING MODULE

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ABSTRACT OF THE DISCLOSURE

A method for preparing a wafer in a cleaning module is described. In this method, slurry is dispensed onto a surface of a wafer. Next, a chemical mechanical planarization (CMP) operation is conducted in the cleaning module by contacting a surface of a brush with the surface of the wafer. Subsequently, a cleaning operation is conducted in the cleaning
10 module. A CMP pad and a CMP system also are described.